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December 2013

FQAF11N90C

N-Channel QFET® MOSFET

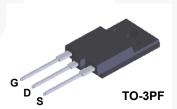
900 V, 7.0 A, 1.1 Ω

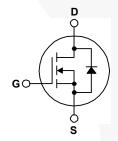
Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

Features

- 7.0 A, 900 V, $R_{DS(on)}$ = 1.1 Ω (Max.) @ V_{GS} = 10 V, I_{D} = 3.5 A
- Low Gate Charge (Typ. 60 nC)
- · Low Crss (Typ. 23 pF)
- 100% Avalanche Tested





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQAF11N90C	Unit
V _{DSS}	Drain-Source Voltage		900	V
I _D	Drain Current - Continuous (T _C = 25°C)		7.0	Α
	- Continuous (T _C = 100°C)		4.4	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	28.0	Α
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		960	mJ
I _{AR}	Avalanche Current	(Note 1)	7.0	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	12	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.0	V/ns
P_D	Power Dissipation (T _C = 25°C)		120	W
	- Derate above 25°C		0.96	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T _L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds.		300	°C

Thermal Characteristics

Symbol	Parameter	FQAF11N90C	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	1.04	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	40	°C/W	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQAF11N90C	FQAF11N90C	TO-3PF	Tube	N/A	N/A	30 units

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Cha	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	900			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		1.0	-	V/°C
Ines	Zero Gate Voltage Drain Current	V _{DS} = 900 V, V _{GS} = 0 V			10	μА
	Zero Gale Vollage Drain Current	V _{DS} = 720 V, T _C = 125°C			100	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 3.5 A		0.91	1.1	Ω
g _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 3.5 A				S
Dynami	ic Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$		2530	3290	pF
C _{oss}	Output Capacitance	f = 1.0 MHz		215	280	pF
C _{rss}	Reverse Transfer Capacitance			23	30	pF
Switchi	ng Characteristics					
t _{d(on)}	Turn-On Delay Time	V 450 V 1 44 0 A		60	130	ns
t _r	Turn-On Rise Time	V_{DD} = 450 V, I_{D} = 11.0 A, R_{G} = 25 Ω		130	270	ns
t _{d(off)}	Turn-Off Delay Time	N _G - 23 12		130	270	ns
t _f	Turn-Off Fall Time	(Note 4)		85	180	ns
Qg	Total Gate Charge	V _{DS} = 720 V, I _D = 11.0 A,		60	80	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V		13		nC
Q _{gd}	Gate-Drain Charge	(Note 4)	/	25		nC
Drain S	ource Diode Characteristics as	nd Maximum Patings				
I _S	Ource Diode Characteristics and Maximum Ratings Maximum Continuous Drain-Source Diode Forward Current				7.0	Α
I _{SM}	Maximum Pulsed Drain-Source Diode F	Forward Current			28.0	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 7.0 A			1.4	V

t_{rr}

 Q_{rr}

Reverse Recovery Time

Reverse Recovery Charge

ns

μC

1000

17.0

 $V_{GS} = 0 \text{ V}, I_S = 11.0 \text{ A},$

 $dI_F / dt = 100 A/\mu s$

Notes: 1. Repetitive rating : pulse-width limited by maximum junction temperature. 2. L = 37 mH, I_{AS} = 7.0 A, V_{DD} = 50 V, R_G = 25 Ω , starting T_J = 25°C . 3. I_{SD} \leq 11.0 A, di/dt \leq 200 A/ μ s, V_{DD} \leq BV_{DSS}, starting T_J = 25°C. 4. Essentially independent of operating temperature.

Typical Characteristics

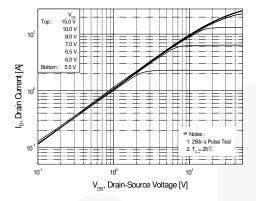


Figure 1. On-Region Characteristics

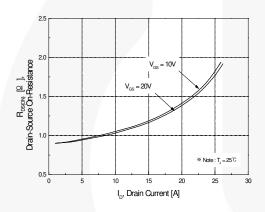


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

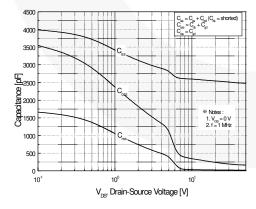


Figure 5. Capacitance Characteristics

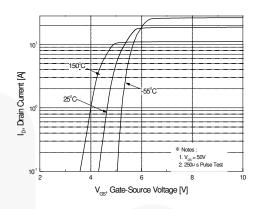


Figure 2. Transfer Characteristics

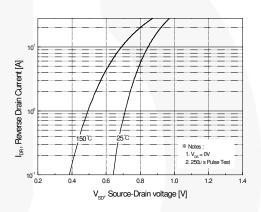


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

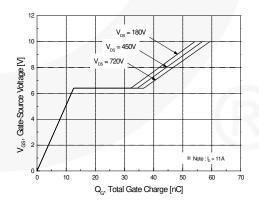


Figure 6. Gate Charge Characteristics

BA 1.1 BY 1.8 BY 1.8

0.8 L -100

Typical Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs Temperature

50

 T_J , Junction Temperature [°C]

100

150

200

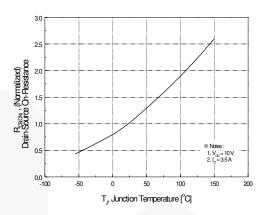


Figure 8. On-Resistance Variation vs Temperature

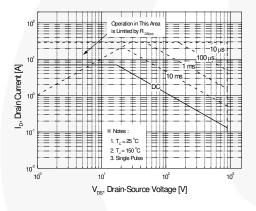


Figure 9. Maximum Safe Operating Area

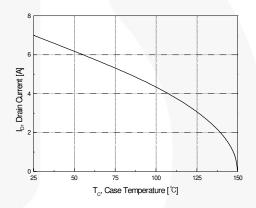


Figure 10. Maximum Drain Current vs Case Temperature

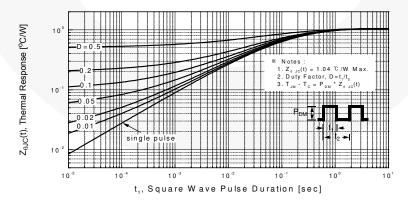


Figure 11. Transient Thermal Response Curve

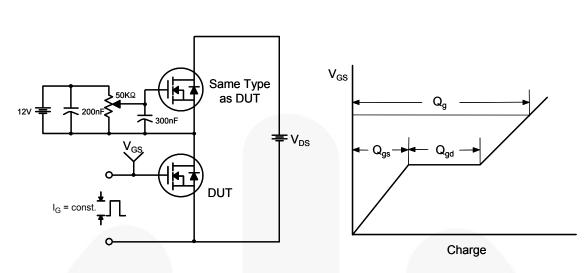


Figure 12. Gate Charge Test Circuit & Waveform

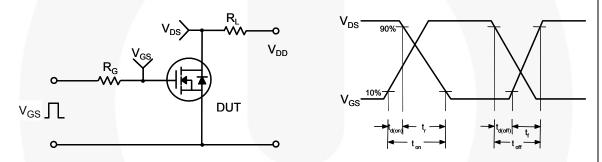


Figure 13. Resistive Switching Test Circuit & Waveforms

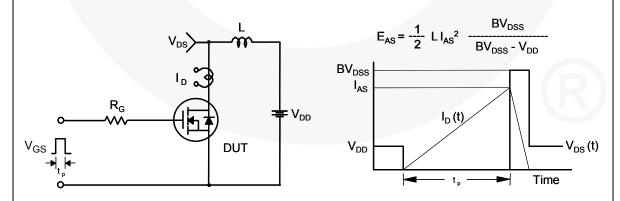
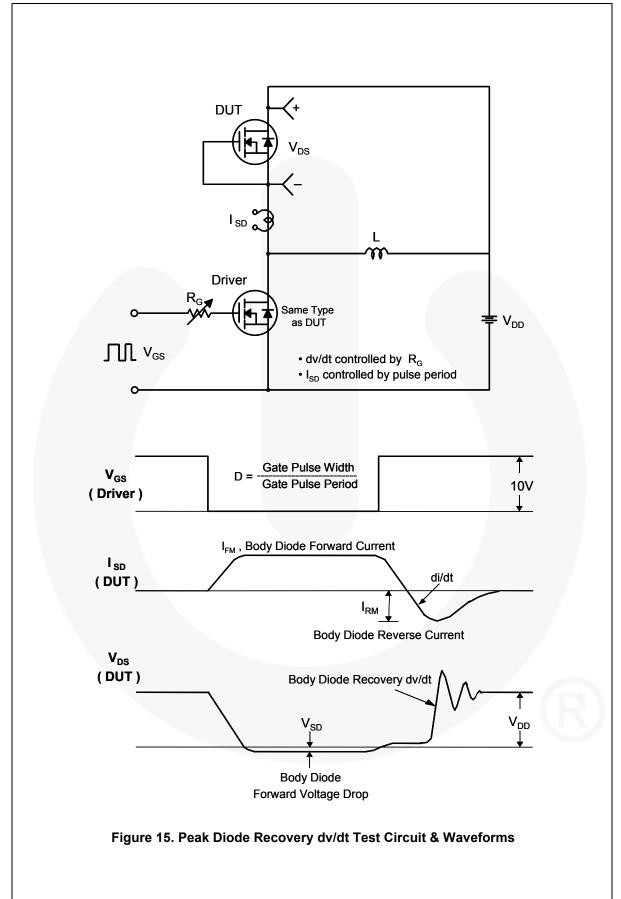


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions

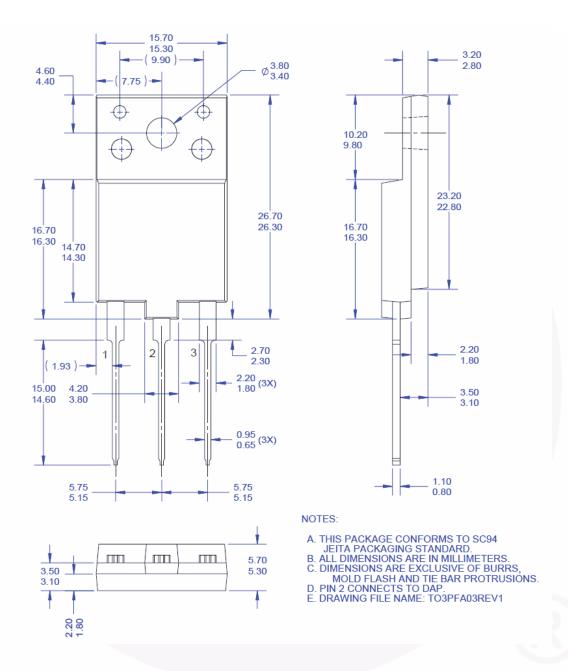


Figure 16. TO3PF, Molded, 3-Lead, Full Pack (AG)

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Rev. 166

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